

EAST Search History

L9	679	L8 and (wafer or semiconductor or chip or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:17
L10	285	L8 and (wafer or semiconductor or chips or dies)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:17
L11	17	(@ad<"20010110") and 438/106. ccls. and ((mold or molding) with (release or liner))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:54
L12	4	(@ad<"20010110") and 257/704. ccls. and ((mold or molding) with (release or liner))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:58
L13	79	(@ad<"20010110") and 438/15,25, 26,51,55,64,106,112,124,126,127. ccls. and ((mold or molding) with (release or liner))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 20:07
L14	155	(@ad<"20010110") and 438/15,25, 26,51,55,64,106,112,124,126,127. ccls. and ((mold or molding) with (release or liner or tape))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 20:21
L15	76	L14 not L13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 20:07
L16	2538	(@ad<"20010110") and (chip or die or wafer) and ((sink or spreader or cap or lid) with (release or liner or tape))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 20:24

EAST Search History

L17	1401	L16 and (mold or moldting or plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 20:24
S1	1	("20060014366").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/09 19:08

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6716666").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/06/09 19:09
L2	5426	Silverbrook	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:09
L3	3093	kia near silverbrook	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:09
L4	414	L3 and caps	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:10
L5	1418	L3 and (cap or caps or lid or lids)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:10
L6	1115	L5 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:11
L7	58	L5 and (wafer adj cap\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:15
L8	3227	(@ad<"20010110") and ((mold or molding) with liner)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/06/09 19:45